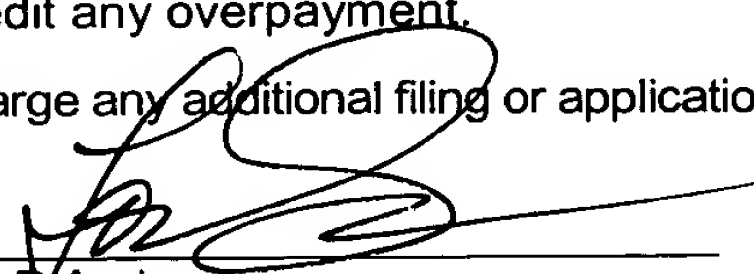


AMENDMENT TRANSMITTAL LETTER			Docket No. M4065.0226/P226		
Application No. 09/484,437-Conf. #9698	Filing Date January 18, 2000	Examiner J. M. Mitchell	Art Unit 2813		
Applicant(s): Tongbi Jiang					
Invention: DIE ATTACH CURING METHOD FOR SEMICONDUCTOR DEVICE					
TO THE COMMISSIONER FOR PATENTS					
Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	33	- 33 =		x	
Independent Claims	2	- 2 =		x	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00
<input checked="" type="checkbox"/> Large Entity <input type="checkbox"/> Small Entity					
<input checked="" type="checkbox"/> No additional fee is required for this amendment.					
<input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of \$ _____. A duplicate copy of this sheet is enclosed.					
<input type="checkbox"/> A check in the amount of \$ _____ to cover the filing fee is enclosed.					
<input type="checkbox"/> Payment by credit card. Form PTO-2038 is attached.					
<input checked="" type="checkbox"/> The Director is hereby authorized to charge and credit Deposit Account No. <u>04-1073</u> as described below. A duplicate copy of this sheet is enclosed.					
<input checked="" type="checkbox"/> Credit any overpayment.					
<input checked="" type="checkbox"/> Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.					
 _____ Thomas J. D'Amico Attorney/Agent Reg. No.: 28,371				Dated: <u>June 12, 2006</u>	
DICKSTEIN SHAPIRO MORIN & OSHINSKY LP 2101 L Street NW Washington, DC 20037-1526 (202) 828-2232					



Docket No.: M4065.0226/P226
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Tongbi Jiang

Application No.: 09/484,437

Confirmation No.: 9698

Filed: January 18, 2000

Art Unit: 2813

For: Die attach curing method for semiconductor
device

Examiner: J. M. Mitchell

AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. 1.116

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated January 11, 2006 (Part of Paper No. 122005), finally rejecting claims 1-3, 5-9, 11, 12, 14, 16-20 and 33-50, please consider the following Remarks.